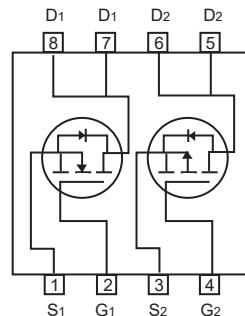
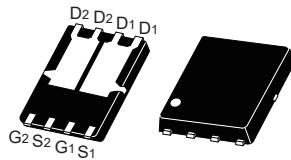


FEATURES

- 40V, 29A, $R_{DS(ON)} = 20.5\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
- -40V, -19.4A, $R_{DS(ON)} = 46\text{m}\Omega$ @ $V_{GS} = -10\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Surface mount Package.



P-PAK 5X6

ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | N-Channel | P-Channel | Units |
|---------------------------------------|--------------------|------------|-----------|-------|
| Drain-Source Voltage | V_{DS} | 40 | -40 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | ± 20 | V |
| Drain Current-Continuous | $I_D @ R_{QJC}$ | 29 | -19.4 | A |
| | $I_D @ R_{QJA}$ | 9.7 | -6.5 | A |
| Drain Current-Pulsed ^a | $I_{DM} @ R_{QJC}$ | 116 | -77.6 | A |
| | $I_{DM} @ R_{QJA}$ | 38.8 | -26 | A |
| Maximum Power Dissipation | P_D | 27.8 | 27.8 | W |
| Operating and Store Temperature Range | T_J, T_{stg} | -55 to 150 | | °C |

Thermal Characteristics

| Parameter | Symbol | Limit | | Units |
|-----------------------------------------|-----------|-------|-----|-------|
| Thermal Resistance, Junction-to-Case | R_{QJC} | 4.5 | 4.5 | °C/W |
| Thermal Resistance, Junction-to-Ambient | R_{QJA} | | 40 | °C/W |

This is preliminary information on a new product in development now .
Details are subject to change without notice .

Rev 1. 2024.Jan
<http://www.cet-mos.com>



CEZ4269A

N-Channel Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---------------------------------------------------------------|----------------------------|------------------------------------------------------------------------------------------------------|-----|------|------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 40 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$ | | 1 | | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$ | | 100 | | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$ | | -100 | | nA |
| On Characteristics^b | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$ | 1 | | 3 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 15\text{A}$ | | 15.5 | 20.5 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$ | | 20 | 26 | $\text{m}\Omega$ |
| Dynamic Characteristics^c | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$ | | 765 | | pF |
| Output Capacitance | C_{oss} | | | 70 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 45 | | pF |
| Switching Characteristics^c | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 20\text{V}, I_D = 10\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 3\Omega$ | | 10 | | ns |
| Turn-On Rise Time | t_r | | | 14 | | ns |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | | 35 | | ns |
| Turn-Off Fall Time | t_f | | | 11 | | ns |
| Total Gate Charge | Q_g | $V_{\text{DS}} = 32\text{V}, I_D = 15\text{A}, V_{\text{GS}} = 10\text{V}$ | | 15 | | nC |
| Gate-Source Charge | Q_{gs} | | | 3 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 3 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current | I_s | | | | 23 | A |
| Drain-Source Diode Forward Voltage ^b | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_s = 1\text{A}$ | | | 1.2 | V |
| Reverse Recovery Time | T_{rr} | $I_F = 6\text{A}, dI/dt = 100\text{A/us}$ | | 18 | | ns |
| Reverse Recovery Charge | Q_{rr} | | | 8 | | nC |

Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature.

b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

c.Guaranteed by design, not subject to production testing.



CEZ4269A

P-Channel Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

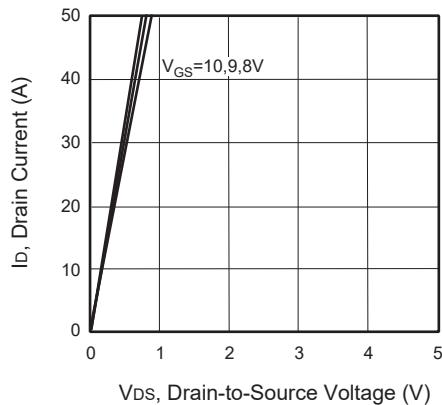
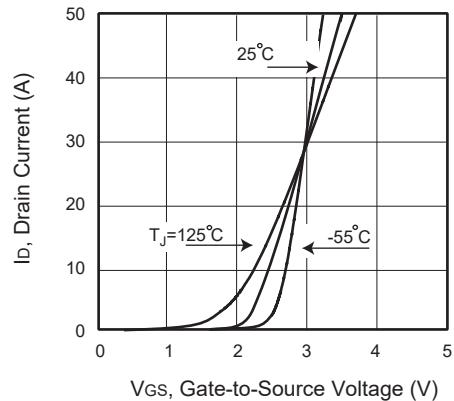
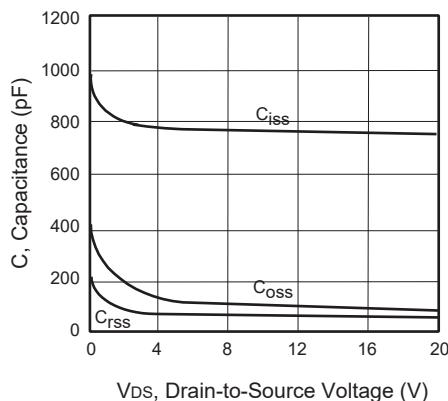
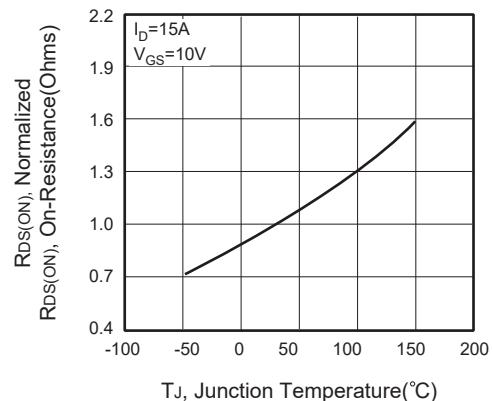
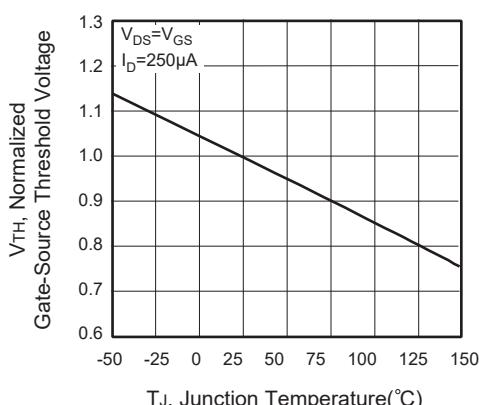
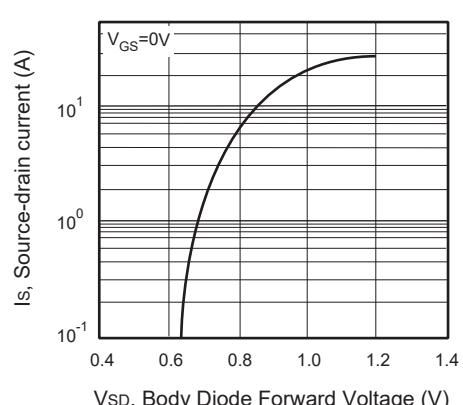
| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|---------------------------------------------------------------|----------------------------|---------------------------------------------------------------------------------------------------------|-----|------|------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$ | -40 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$ | | | -1 | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$ | | | 100 | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$ | | | -100 | nA |
| On Characteristics^b | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$ | -1 | | -3 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = -10\text{V}, I_D = -15\text{A}$ | | 35 | 46 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = -4.5\text{V}, I_D = -10\text{A}$ | | 46 | 60 | $\text{m}\Omega$ |
| Dynamic Characteristics^c | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$ | | 1050 | | pF |
| Output Capacitance | C_{oss} | | | 60 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 55 | | pF |
| Switching Characteristics^c | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = -20\text{V}, I_D = -10\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 3\Omega$ | | 15 | | ns |
| Turn-On Rise Time | t_r | | | 12 | | ns |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | | 187 | | ns |
| Turn-Off Fall Time | t_f | | | 80 | | ns |
| Total Gate Charge | Q_g | $V_{\text{DS}} = -20\text{V}, I_D = -10\text{A}, V_{\text{GS}} = -10\text{V}$ | | 21 | | nC |
| Gate-Source Charge | Q_{gs} | | | 2 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 6 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current | I_S | | | | -19 | A |
| Drain-Source Diode Forward Voltage ^b | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_S = -1\text{A}$ | | | -1.2 | V |
| Reverse Recovery Time | T_{rr} | $I_F = -6\text{A}, dI/dt = 100\text{A}/\mu\text{s}$ | | 14 | | ns |
| Reverse Recovery Charge | Q_{rr} | | | 9 | | nC |

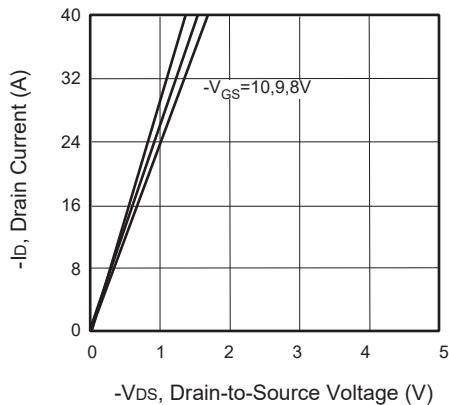
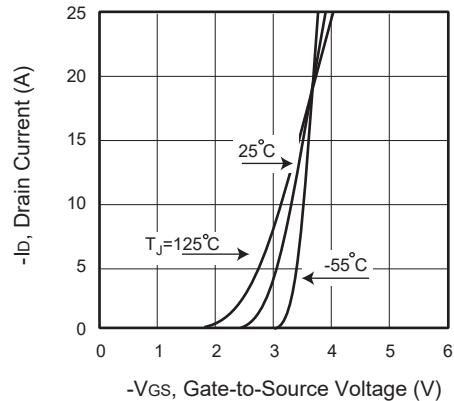
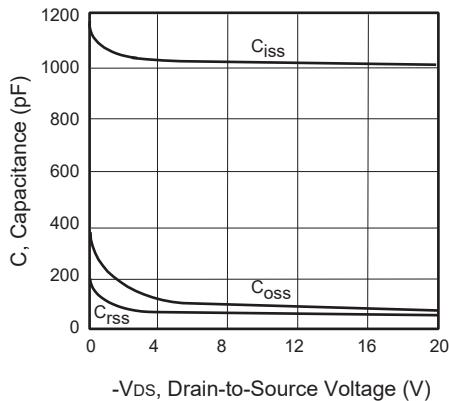
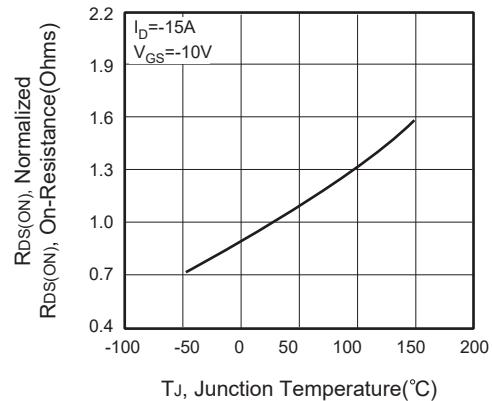
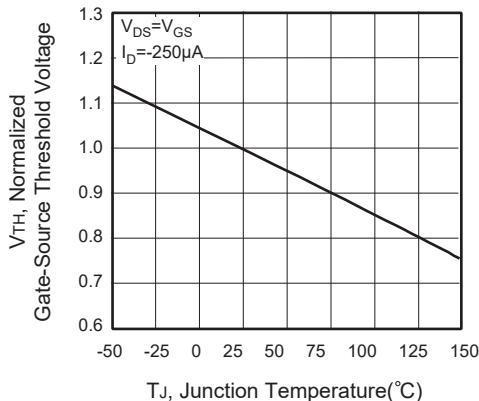
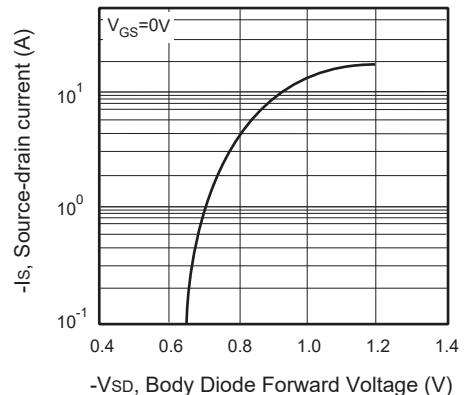
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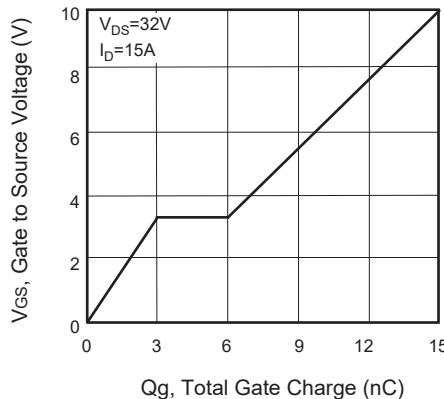
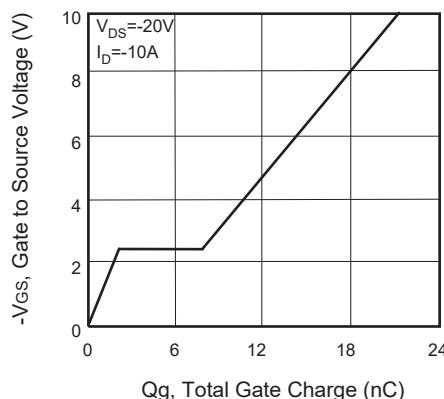
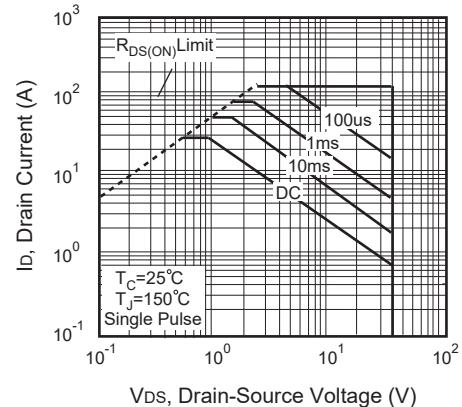
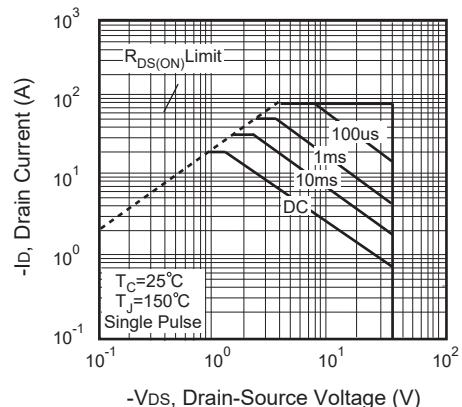
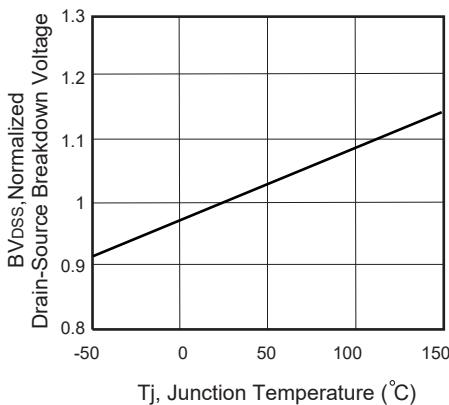
a.Repetitive Rating : Pulse width limited by maximum junction temperature.

b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

c.Guaranteed by design, not subject to production testing.

N-CHANNEL

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Capacitance

Figure 4. On-Resistance Variation with Temperature

Figure 5. Gate Threshold Variation with Temperature

Figure 6. Body Diode Forward Voltage Variation with Source Current

P-CHANNEL

Figure 7. Output Characteristics

Figure 8. Transfer Characteristics

Figure 9. Capacitance

Figure 10. On-Resistance Variation with Temperature

Figure 11. Gate Threshold Variation with Temperature

Figure 12. Body Diode Forward Voltage Variation with Source Current

N-CHANNEL

Figure 13. Gate Charge
P-CHANNEL

Figure 15. Gate Charge

Figure 14. Maximum Safe Operating Area

Figure 16. Maximum Safe Operating Area

Figure 17. Breakdown Voltage Variation VS Temperature

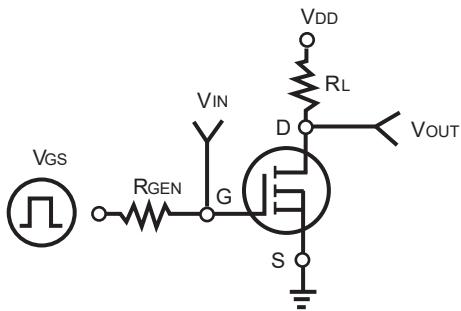


Figure 18. Switching Test Circuit

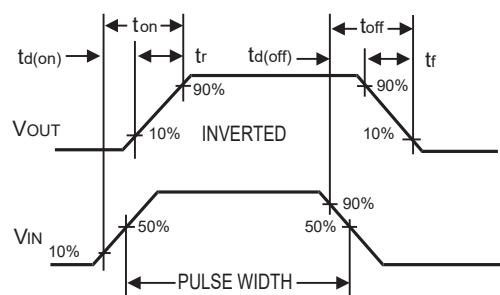


Figure 19. Switching Waveforms

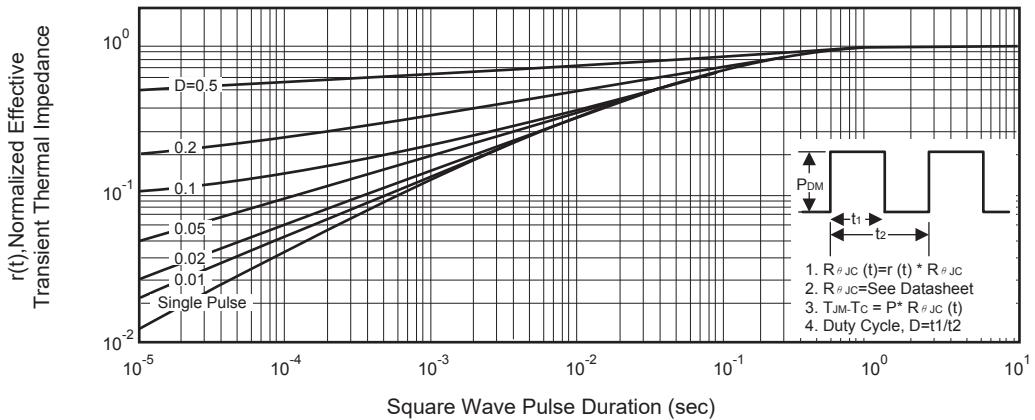


Figure 20. Normalized Thermal Transient Impedance Curve